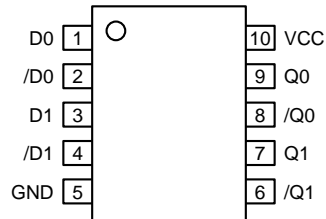


## PACKAGE/ORDERING INFORMATION



10-Pin MSOP (K10-1)

Ordering Information<sup>(1)</sup>

Part Number	Package Type	Operating Range	Package Marking	Lead Finish
SY55857LKI	K10-1	Industrial	857L	Sn-Pb
SY55857LKITR <sup>(2)</sup>	K10-1	Industrial	857L	Sn-Pb
SY55857LKG <sup>(3)</sup>	K10-1	Industrial	857L with Pb-Free bar line indicator	NiPdAu Pb-Free
SY55857LKGTR <sup>(2, 3)</sup>	K10-1	Industrial	857L with Pb-Free bar line indicator	NiPdAu Pb-Free

## Notes:

1. Contact factory for die availability. Dice are guaranteed at  $T_A = 25^\circ\text{C}$ , DC Electricals only.
2. Tape and Reel.
3. Pb-Free package recommended for new designs.

## PIN DESCRIPTIONS

Pin Number	Pin Name	Description
D0, /D0	1, 2	Channel 0 Differential Inputs (clock or data). See Figure 2 for input structure. See "Input Interface" section for typical interface recommendations.
D1, /D1	3, 4	Channel 1 Differential Inputs (clock or data). See Figure 2 for input structure. See "Input Interface" section for typical interface recommendations.
Q0, /Q0	9, 8	Channel 0 Differential 100k-compatible LVPECL Outputs. Terminate to $V_{CC} - 2V$ . See "LVPECL Output Termination" section. Outputs are low impedance, emitter-followers. For AC-coupled applications, a pull-down resistor is required on Q and /Q to ensure a DC current path to GND.
Q1, /Q1	7, 6	Channel 1 Differential 100k-compatible LVPECL Outputs. Terminate to $V_{CC} - 2V$ . See "LVPECL Output Termination" section. Outputs are low impedance, emitter-followers. For AC-coupled applications, a pull-down resistor is required on Q and /Q to ensure a DC current path to GND.
GND	5	Device Ground. Typically connected to Logic ground.
$V_{CC}$	10	Supply Voltage. Typically connect to $+3.3V \pm 10\%$ supply. Bypass with $0.01\mu F    0.1\mu F$ low ESR capacitors.

**Absolute Maximum Ratings<sup>(1)</sup>**

Power Supply Voltage ( $V_{CC}$ )	..... -0.5V to +6.0V
Input Voltage ( $V_{IN}$ )	..... -0.5V to $V_{CC} + 0.5V$
Output Current ( $I_{OUT}$ )	
Continuous	..... 50mA
Surge	..... 100mA
Lead Temperature (soldering, 20 sec.)	..... +260°C
Storage Temperature Range ( $T_S$ )	..... -65°C to +150°C

**Operating Ratings<sup>(2)</sup>**

Power Supply Voltage ( $V_{CC}$ )	..... +3.0V to +3.6V
Ambient Temperature Range ( $T_A$ )	..... -40°C to +85°C
Package Thermal Resistance <sup>(3)</sup>	
MSOP ( $\theta_{JA}$ )	
Still-Air	..... 113°C/W
500lpm	..... 96°C/W
MSOP ( $\theta_{JC}$ )	
Junction-to-Case	..... 42°C/W

**DC ELECTRICAL CHARACTERISTICS<sup>(4)</sup>** $T_A = -40^\circ\text{C}$  to  $+85^\circ\text{C}$ ; unless noted.

Symbol	Parameter	Condition	Min	Typ	Max	Units
$V_{CC}$	Power Supply Voltage		3.0	3.3	3.6	V
$I_{CC}$	Power Supply Current	Inputs/outputs open		28	45	mA

**INPUT ELECTRICAL CHARACTERISTICS<sup>(4)</sup>** $V_{CC} = +3.0V$  to  $+3.6V$ ; GND = 0V;  $T_A = -40^\circ\text{C}$  to  $+85^\circ\text{C}$ ; unless noted.

Symbol	Parameter	Condition	Min	Typ	Max	Units
$V_{ID}$	Input Voltage Swing	See Figure 1a, $V_{IN} < 2.4V$ .	100			mV
		$V_{IN} < V_{CC} + 0.3V$	200			mV
$V_{IH}$	Input HIGH Voltage				$V_{CC} + 0.3$	V
$V_{IL}$	Input LOW Voltage		-0.3			V

**(100K) LVPECL OUTPUT CHARACTERISTICS<sup>(5)</sup>** $V_{CC} = +3.0V$  to  $+3.6V$ ; GND = 0V;  $T_A = -40^\circ\text{C}$  to  $+85^\circ\text{C}$ ;  $R_L = 50\Omega$  to  $V_{CC} - 2V$ , unless otherwise stated.

Symbol	Parameter	Condition	Min	Typ	Max	Units
$V_{OL}$	Output LOW Voltage Q, /Q		$V_{CC} - 1.945$	$V_{CC} - 1.820$	$V_{CC} - 1.695$	V
$V_{OH}$	Output HIGH Voltage Q, /Q		$V_{CC} - 1.145$	$V_{CC} - 1.020$	$V_{CC} - 0.895$	V
$V_{OUT}$	Output Voltage Swing Q, /Q	See Figure 1a.	550	800		mV
$V_{DIFF\_OUT}$	Differential Output Voltage Swing Q, /Q	See Figure 1b.	1100	1600		mV <sub>pp</sub>

**Notes:**

1. Permanent device damage may occur if the ratings in "Absolute Maximum Ratings" section are exceeded. This is a stress rating only and functional operation is not implied at conditions other than those detailed in the operational sections of this data sheet. Exposure to absolute maximum ratings conditions for extended periods may affect device reliability.
2. The data sheet limits are not guaranteed if the device is operated beyond the operating ratings.
3. Package thermal resistance assumes exposed pad is soldered (or equivalent) to the device's most negative potential (GND) on the PCB.  $\psi_{JB}$  uses 4-layer  $\theta_{JA}$  in still air unless otherwise stated.
4. The specifications shown are valid after thermal equilibrium has been established.
5. 100K circuits are designed to meet the DC specifications shown in the above table after thermal equilibrium has been established.

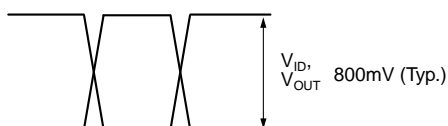
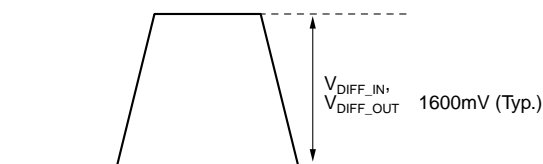
**AC ELECTRICAL CHARACTERISTICS**

$V_{CC} = 3.3V \pm 10\%$ ;  $T_A = -40^\circ C$  to  $+85^\circ C$ ;  $R_L = 50\Omega$  to  $V_{CC} - 2V$ , unless otherwise stated.

Symbol	Parameter	Condition	Min	Typ	Max	Units
$f_{MAX}$	Maximum Operating Frequency <b>Note 6</b>	$V_{IN} < 2.4V$ NRZ Data	2.5			Gbps
		$V_{IN} < 2.4V$ Clock	2.5			GHz
		$V_{IN} < V_{CC} + 0.3V$ NRZ Data	1.25			Gbps
		$V_{IN} < V_{CC} + 0.3V$ Clock	1.25			GHz
$t_{PD}$	Propagation Delay D-to-Q				400	ps
$t_{SKEW}$	Within-Device-Skew (Differential)	<b>Note 7</b>			50	ps
	Part-to-Part Skew (Differential)	<b>Note 8</b>			200	ps
$t_{JITTER}$	Random Jitter (RJ)	<b>Note 9</b>			1	ps <sub>RMS</sub>
	Deterministic Jitter (DJ)	<b>Note 10</b>			10	ps <sub>pp</sub>
	Total Jitter (TJ)	<b>Note 11</b>		1	10	ps <sub>pp</sub>
$t_r, t_f$	Output Rise/Fall Time 20% to 80%	At full output swing			200	ps

**Notes:**

6. Clock frequency is defined as the maximum toggle frequency, and guaranteed for functionality only. Measured with a 750mV signal, 50% duty cycle and  $V_{OUT}$  swing  $\geq 400mV$ . High -frequency AC-parameters are guaranteed by design and characterization.
7. Within-device skew is measured between two different outputs under identical transitions.
8. Part-to-part skew is defined for two parts with identical power supply voltages at the same temperature and with no skew of the edges at the respective inputs.
9. Random jitter is measured with a K28.7 comma detect character pattern, measured at 2.5Gbps.
10. Deterministic jitter is measured at 2.5Gbps with both K28.5 and 2<sup>23</sup>-1 PRBS pattern.
11. Total jitter definition: with an ideal differential clock input of frequency  $\leq f_{MAX}$ , no more than one output edge in 10<sup>12</sup> output edges will deviate by more than the specified peak-to-peak jitter value.

**SINGLE-ENDED AND DIFFERENTIAL SWINGS****Figure 1a. Single-Ended Voltage Swing****Figure 1b. Differential Voltage Swing**

## FUNCTIONAL DESCRIPTION

### Establishing Static Logic Inputs

Do not leave unused inputs floating. Tie either the true or complement inputs to ground, but not both. A logic zero is achieved by connecting the complement input to ground with the true input floating. For a TTL input, tie a 2.5kΩ resistor between the complement input and ground. See "Input Interface" section.

### Input Levels

LVDS, CML and HSTL differential signals may be connected directly to the D inputs. Depending on the actual worst case voltage seen, performance of SY55857L varies as per the following table:

Input Voltage Range	Minimum Voltage Swing	Maximum Translation Speed
0 to 2.4V	100mV	2.5Gbps
0 to $V_{CC} + 0.3$	200mV	1.25Gbps

Table 1. Input Voltage Swings

For LVDS applications, only point-to-point interfaces are supported. Due to the current required by the input structure shown in Figure 2, multi-drop and multi-point architectures are not supported.

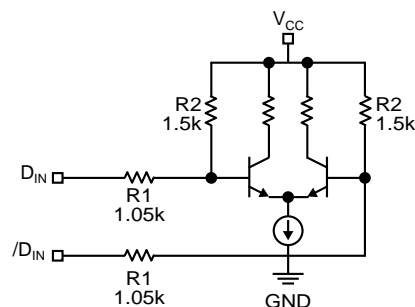
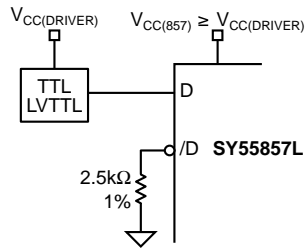
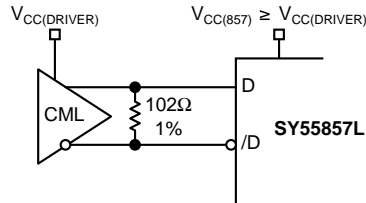
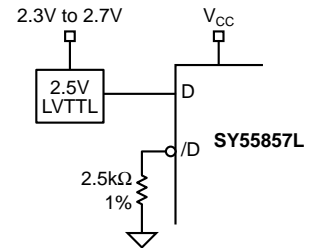
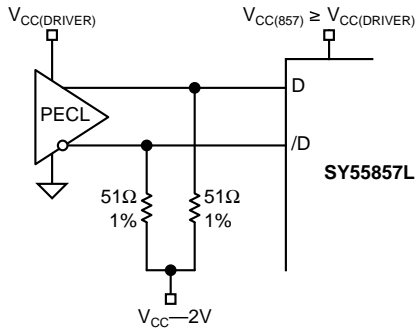
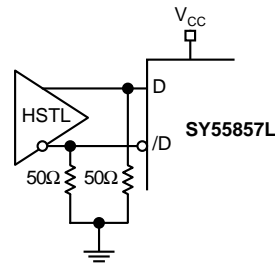
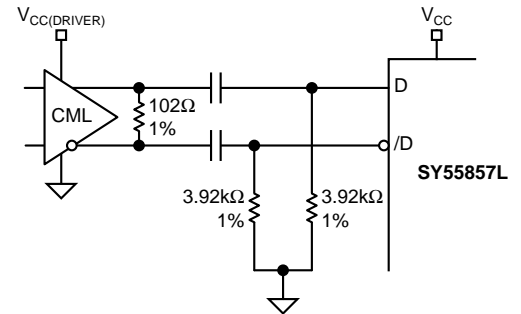
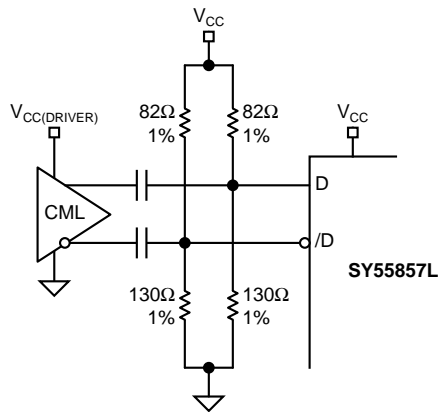
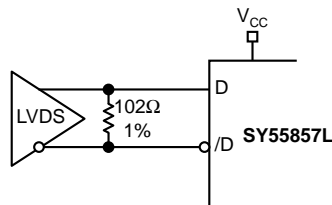
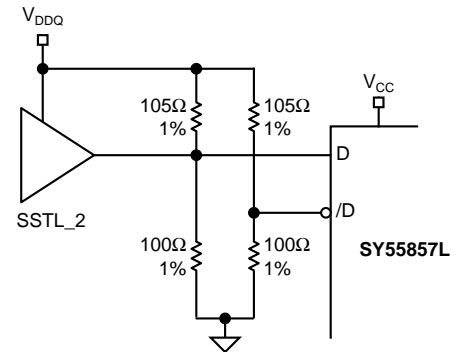
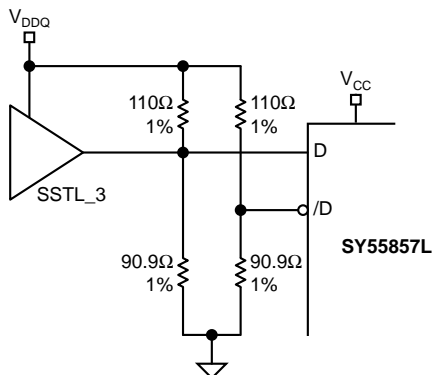
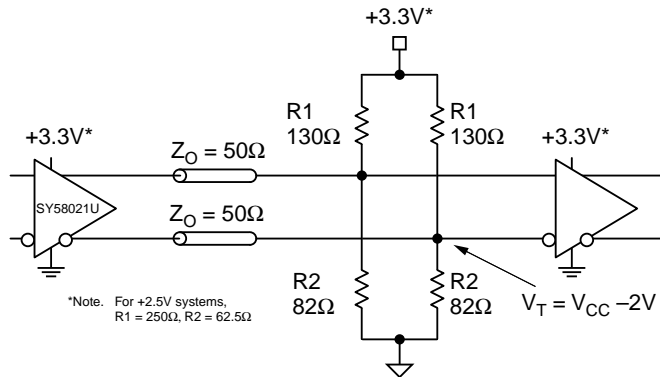


Figure 2. Simplified Input Structure

**INPUT INTERFACE****Figure 3. 3.3V "TTL"****Figure 4. CML-DC Coupled****Figure 5. 2.5V "TTL"****Figure 6. PECL-DC Coupled****Figure 7. HSTL****Figure 8. CML-AC Coupled Short Lines****Figure 9. CML-AC Coupled Long Lines****Figure 10. LVDS****Figure 11. SSTL\_2****Figure 12. SSTL\_3**

## LVPECL OUTPUT TERMINATION

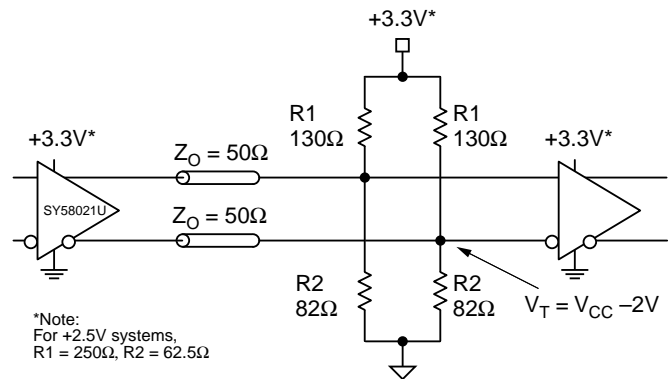
LVPECL output have very low output impedance (open emitter), and small signal swing which results in low EMI. LVPECL is ideal for driving 50Ω and 100Ω-controlled impedance transmission lines. There are several techniques in terminating the LVPECL output, as shown in Figures 13 through 15.



**Figure 13. Parallel Termination-Thevenin Equivalent**

**Notes:**

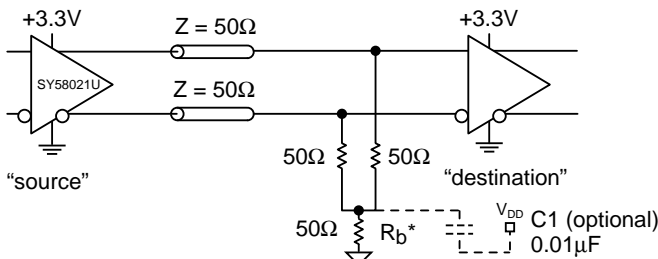
1. For +2.5V systems: R1 = 250Ω, R2 = 62.5Ω.
2. For +3.3V systems: R1 = 130Ω, R2 = 82Ω.



**Figure 15. Terminating Unused I/O**

**Notes:**

1. Unused output (/Q) must be terminated to balance the output.
2. For +2.5V systems: R1 = 250Ω, R2 = 62.5Ω, R3 = 1.25kΩ, R4 = 1.2kΩ.  
For +3.3V systems: R1 = 130Ω, R2 = 82Ω, R3 = 1kΩ, R4 = 1.6kΩ.
3. Unused output pairs (Q and /Q) may be left floating.



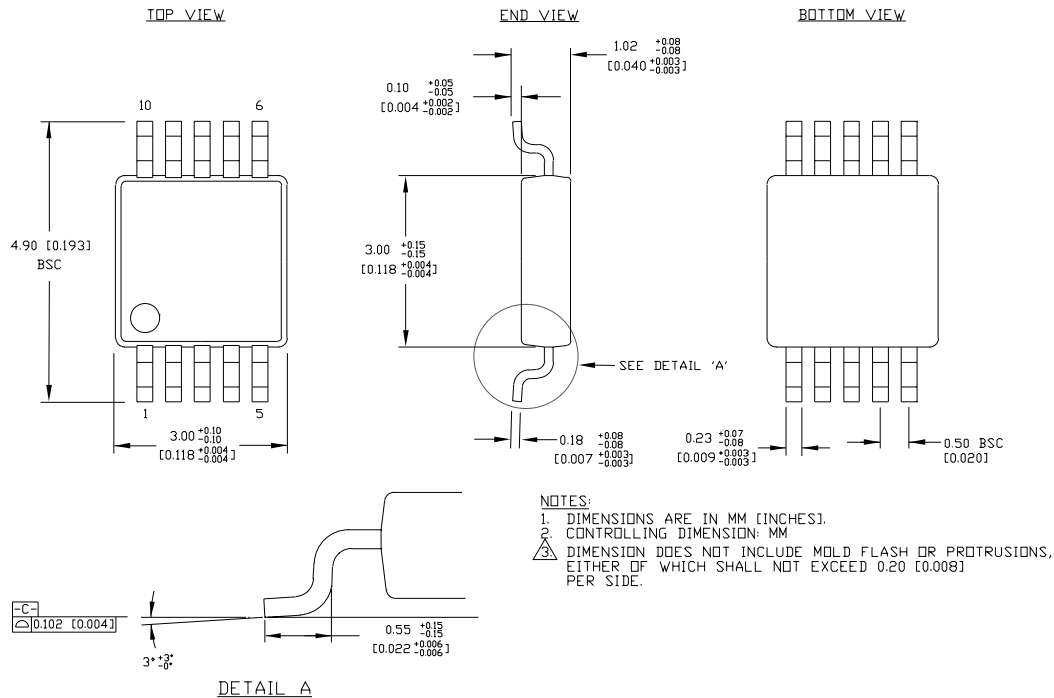
**Notes:**

1. Power saving alternative to Thevenin termination.
2. Place termination resistors as close to destination inputs as possible.
3. Rb resistor sets the DC bias voltage, equal to V\_T.

**Figure 14. Three-Resistor "Y-Termination"**

**Notes:**

1. Power-saving alternatives to Thevenin termination.
2. Place termination resistors as close to destination inputs as possible.
3. Rb resistor sets the DC bias voltage, equal to V\_T.  
For +2.5V systems: R\_b = 19Ω.  
For +3.3V systems: R\_b = 46Ω to 50Ω.
4. C1 is an optional bypass capacitor intended to compensate for any t\_r/t\_f mismatches.

**10-PIN MSOP (K10-1)**

Rev. 00

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